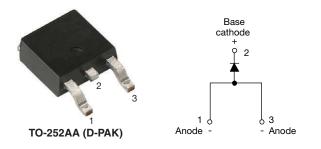
**Vishay Semiconductors** 

# High Voltage Surface Mount Input Rectifier Diode, 8 A



www.vishay.com

PRODUCT SUMMARY								
Package	TO-252AA (D-PAK)							
I <sub>F(AV)</sub>	8 A							
V <sub>R</sub>	800 V, 1200 V							
$V_F$ at $I_F$	1.1 V							
I <sub>FSM</sub>	150 A							
T <sub>J</sub> max.	150 °C							
Diode variation	Single die							

### **FEATURES**

- · Glass passivated pellet chip junction
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

### APPLICATIONS

- Input rectification
- Vishay Semiconductors switches and output rectifiers which are available in identical package outlines

### DESCRIPTION

The 8EWS..SPbF rectifier high voltage series has been optimized for very low forward voltage drop, with moderate leakage. The glass passivation technology used has reliable operation up to 150 °C junction temperature.

The high reverse voltage range available allows design of input stage primary rectification with outstanding voltage surge capability.

OUTPUT CURRENT IN TYPICAL APPLICATIONS									
APPLICATIONS	SINGLE-PHASE BRIDGE	UNITS							
NEMA FR-4 or G10 glass fabric-based epoxy with 4 oz. (140 µm) copper	1.2	1.6							
Aluminum IMS, R <sub>thCA</sub> = 15 °C/W	2.5	2.8	А						
Aluminum IMS with heatsink, $R_{thCA} = 5 \text{ °C/W}$	5.5	6.5							

### Note

T<sub>A</sub> = 55 °C, T<sub>J</sub> = 125 °C, footprint 300 mm<sup>2</sup>

MAJOR RATINGS AND CHARACTERISTICS								
SYMBOL	CHARACTERISTICS	VALUES	UNITS					
I <sub>F(AV)</sub>	Sinusoidal waveform at $T_C = 116 \ ^{\circ}C$	8	A					
V <sub>RRM</sub>		800/1200	V					
I <sub>FSM</sub>		150	A					
V <sub>F</sub>	8 A, T <sub>J</sub> = 25 °C	1.10	V					
TJ		-55 to +150	°C					

VOLTAGE RATINGS									
PART NUMBER	V <sub>RRM</sub> , MAXIMUM PEAK REVERSE VOLTAGE V	V <sub>RSM</sub> , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I <sub>RRM</sub> AT 150 °C mA						
8EWS08SPbF	800	900	0.5						
8EWS12SPbF	1200	1300	0.5						

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## **VS-8EWS..SPbF Series**



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ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS					
Maximum average forward current	I <sub>F(AV)</sub>	$T_C$ = 105 °C, 180° conduction half sine wave	8						
Maximum peak one cycle		10 ms sine pulse, rated $V_{\text{RRM}}$ applied	125	А					
non-repetitive surge current	IFSM	10 ms sine pulse, no voltage reapplied	150						
Maximum I <sup>2</sup> t for fusing	l <sup>2</sup> t	10 ms sine pulse, rated $V_{RRM}$ applied	78	A <sup>2</sup> s					
Maximum 1-t for fusing	1-1	10 ms sine pulse, no voltage reapplied	110	A-2					
Maximum I <sup>2</sup> $\sqrt{t}$ for fusing	l²√t	t = 0.1 ms to 10 ms, no voltage reapplied	1100	A²√s					

ELECTRICAL SPECIFICATIONS									
PARAMETER	SYMBOL	TEST CO	VALUES	UNITS					
Maximum forward voltage drop	V <sub>FM</sub>	8 A, T <sub>J</sub> = 25 °C	1.1	V					
Forward slope resistance	r <sub>t</sub>	T <sub>.1</sub> = 150 °C	20	mΩ					
Threshold voltage	V <sub>F(TO)</sub>	1j = 150 C	0.82	V					
Maximum reverse leakage current		T <sub>J</sub> = 25 °C		0.05	<b>m</b> (				
Maximum reverse leakage current	IRM	T <sub>J</sub> = 150 °C	V <sub>R</sub> = Rated V <sub>RRM</sub>	0.50	mA				

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-55 to +150	°C
Maximum thermal resistance, junction to case	R <sub>thJC</sub>	DC operation	2.5	00 AN
Typical thermal resistance, junction to ambient (PCB mount)	R <sub>thJA (1)</sub>		62	°C/W
Annyovimete weight			1	g
Approximate weight			0.03	oz.
Marking device		Case style TO-252AA (D-PAK)	8EWS	S12S

Note

<sup>(1)</sup> When mounted on 1" square (650 mm<sup>2</sup>) PCB of FR-4 or G-10 material 4 oz. (140 µm) copper 40 °C/W For recommended footprint and soldering techniques refer to application note #AN-994



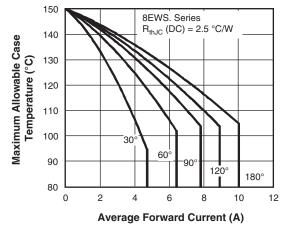


Fig. 1 - Current Rating Characteristics

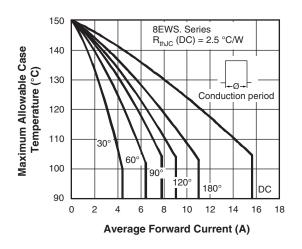


Fig. 2 - Current Rating Characteristics

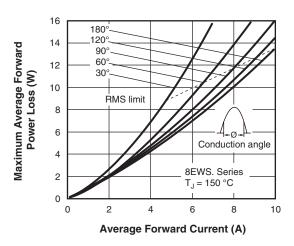


Fig. 3 - Forward Power Loss Characteristics

### **VS-8EWS..SPbF Series**

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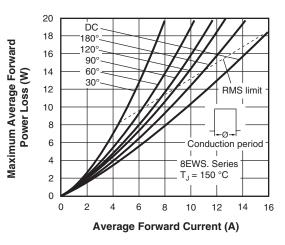
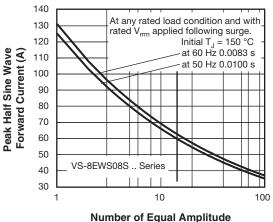
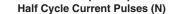


Fig. 4 - Forward Power Loss Characteristics







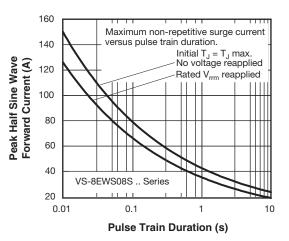


Fig. 6 - Maximum Non-Repetitive Surge Current

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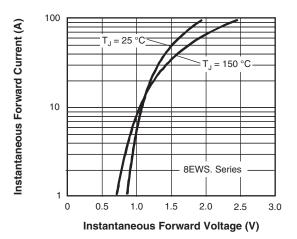


Fig. 7 - Forward Voltage Drop Characteristics

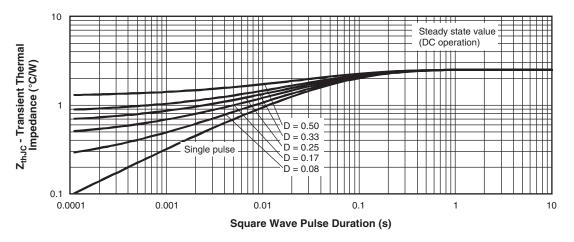


Fig. 8 - Thermal Impedance ZthJC Characteristics

**VS-8EWS..SPbF Series** 

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Device code	VS-	8	E	w	S	12	S	TR	PbF
	1	2	3	4	5	6	7	8	9
	1 - 2 - 3 - 4 -	Cur Circ E = Pac W =	rent rati suit confi single c kage: D-PAK	ng (8 = 8 iguratior liode	-	duct			
	5 - 6 - 7 - 8 -	S = Volt S =	age rati surface	d recove		(	08 = 800 2 = 120		
	9 -	• TF	RL = tap		eel (righ eel (left d e				

LINKS TO RELATED DOCUMENTS							
Dimensions	www.vishay.com/doc?95016						
Part marking information	www.vishay.com/doc?95059						
Packaging information	www.vishay.com/doc?95033						

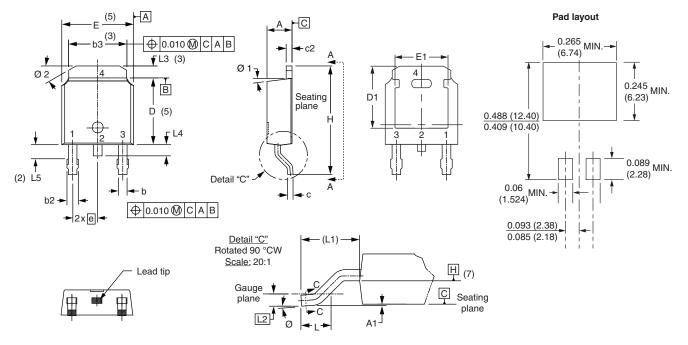






D-PAK (TO-252AA)

### **DIMENSIONS** in millimeters and inches



SYMBOL	MILLIMETERS		INC	HES	NOTES	NOTES		MILLIN	IETERS	INC	HES	NOTES
STMIDUL	MIN.	MAX.	MIN.	MAX.	NOTES		SYMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
А	2.18	2.39	0.086	0.094			е	2.29	BSC	0.090	BSC	
A1	-	0.13	-	0.005			Н	9.40	10.41	0.370	0.410	
b	0.64	0.89	0.025	0.035			L	1.40	1.78	0.055	0.070	
b2	0.76	1.14	0.030	0.045			L1	2.74	BSC	0.108	REF.	
b3	4.95	5.46	0.195	0.215	3		L2	0.51	BSC	0.020	BSC	
С	0.46	0.61	0.018	0.024			L3	0.89	1.27	0.035	0.050	3
c2	0.46	0.89	0.018	0.035			L4	-	1.02	-	0.040	
D	5.97	6.22	0.235	0.245	5		L5	1.14	1.52	0.045	0.060	2
D1	5.21	-	0.205	-	3		Ø	0°	10°	0°	10°	
E	6.35	6.73	0.250	0.265	5		Ø1	0°	15°	0°	15°	
E1	4.32	-	0.170	-	3		Ø2	25°	35°	25°	35°	

### Notes

<sup>(1)</sup> Dimensioning and tolerancing as per ASME Y14.5M-1994

(2) Lead dimension uncontrolled in L5

<sup>(3)</sup> Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad

(4) Section C - C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip

(5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

<sup>(6)</sup> Dimension b1 and c1 applied to base metal only

<sup>(7)</sup> Datum A and B to be determined at datum plane H

<sup>(8)</sup> Outline conforms to JEDEC outline TO-252AA

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